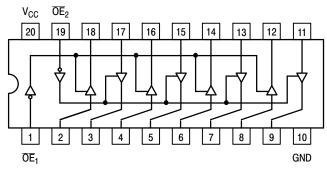
Octal Buffer/Line Driver with 3-State Outputs

The MC74AC244/74ACT244 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter/receiver which provides improved PC board density.

Features

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- 'ACT244 Has TTL Compatible Inputs
- These are Pb–Free Devices



Pinout: 20-Lead Packages Conductors (Top View)

TRUTH TABLE

Inputs		Outputs
OE ₁ D		(Pins 12, 14, 16, 18)
L	L	L
L	Н	Н
Н	Χ	Z

NOTE: H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

TRUTH TABLE

Inputs		Outputs
ŌĒ ₂ D		(Pins 3, 5, 7, 9)
L	L	L
L	Н	Н
Н	Х	Z

NOTE: H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance



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SOIC-20W **DW SUFFIX CASE 751D**



TSSOP-20 **DT SUFFIX CASE 948E**

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)		-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)		–0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND) (Note 1)		-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±50	mA
I _{OUT}	DC Output Sink/Source Current		±50	mA
I _{CC}	DC Supply Current, per Output Pin		±50	mA
I _{GND}	DC Ground Current, per Output Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		140	°C
θ_{JA}	Thermal Resistance (Note 2)	SOIC TSSOP	65.8 110.7	°C/W
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen Index	k: 30% – 35%	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body M Machine M Charged Device M	lodel (Note 4)	> 2000 > 200 > 1000	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 8	35°C (Note 6)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I_{OUT} absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD 51–7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit		
\/	Complex Valtages	'AC	2.0	5.0	6.0	V	
V _{CC}	Supply Voltage	'ACT	4.5	5.0	5.5	V	
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V _{CC}	V	
		V _{CC} @ 3.0 V	-	150	-		
t _r , t _f	Input Rise and Fall Time (Note 7) 'AC Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	40	-	ns/V	
	The Bevices except commit inputs	V _{CC} @ 5.5 V	-	25	-		
	Input Rise and Fall Time (Note 8)	V _{CC} @ 4.5 V	_	10	-	0/	
t _r , t _f	'ACT Devices except Schmitt Inputs	V _{CC} @ 5.5 V	-	8.0	-	ns/V	
T _A	Operating Ambient Temperature Range	-40	25	85	°C		
I _{OH}	Output Current – High	-	-	-24	mA		
I _{OL}	Output Current – Low		-	_	24	mA	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
 V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

			74.	AC	74AC			
Symbol	Parameter	V _{CC} (V)	T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions	
			Тур	Gua	ranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V	
V _{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I _{OUT} = -50 μA	
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA	
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I _{OUT} = 50 μA	
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA	
I _{IN}	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V _I = V _{CC} , GND	
l _{OZ}	Maximum 3–State Current	5.5	-	±0.5	±5.0	μΑ	V_{I} (OE) = V_{IL} , V_{IH} V_{I} = V_{CC} , GND V_{O} = V_{CC} , GND	
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	ı	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	_	8.0	80	μΑ	$V_{IN} = V_{CC}$ or GND	

^{*}All outputs loaded; thresholds on input associated with output under test.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} .

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

				74AC		74	AC		
Symbol	Parameter	Parameter V_{CC}^* (V)		T _A = +25°C C _L = 50 pF			$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 50 \text{ pF}$		Figure No.
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay Data to Output	3.3 5.0	2.0 1.5	6.5 5.0	9.0 7.0	1.5 1.0	10.0 7.5	ns	3–5
t _{PHL}	Propagation Delay Data to Output	3.3 5.0	2.0 1.5	6.5 5.0	9.0 7.0	2.0 1.0	10.0 7.5	ns	3–5
t _{PZH}	Output Enable Time	3.3 5.0	2.0 1.5	6.0 5.0	10.5 7.0	1.5 1.5	11.0 8.0	ns	3–7
t _{PZL}	Output Enable Time	3.3 5.0	2.5 1.5	7.5 5.5	10.0 8.0	2.0 1.5	11.0 8.5	ns	3–8
t _{PHZ}	Output Disable Time	3.3 5.0	3.0 2.5	7.0 6.5	10.0 9.0	1.5 1.0	10.5 9.5	ns	3–7
t _{PLZ}	Output Disable Time	3.3 5.0	2.5 2.0	7.5 6.5	10.5 9.0	2.5 2.0	11.5 9.5	ns	3–8

[†]Maximum test duration 2.0 ms, one output loaded at a time.

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. *Voltage Range 5.0 V is 5.0 V ± 0.5 V.

DC CHARACTERISTICS

			74	CT	74ACT			
Symbol	Parameter	V _{CC} (V)	T _A = -	$T_A = +25^{\circ}C$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Unit	Conditions	
			Тур	Gua	ranteed Limits			
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V	
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V	
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = -50 μA	
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	* V _{IN} = V _{IL} or V _{IH} -24 mA $_{OH}$ -24 mA	
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA	
		4.5 5.5	_ _	0.36 0.36	0.44 0.44	V	$^*V_{IN} = V_{IL} \text{ or } V_{IH}$ $^{24} \text{ mA}$ I_{OL} $^{24} \text{ mA}$	
I _{IN}	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	$V_I = V_{CC}$, GND	
ΔI_{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	_	1.5	mA	$V_{I} = V_{CC} - 2.1 \text{ V}$	
l _{OZ}	Maximum 3–State Current	5.5	-	±0.5	±5.0	μΑ	V_{I} (OE) = V_{IL} , V_{IH} V_{I} = V_{CC} , GND V_{O} = V_{CC} , GND	
I _{OLD}	†Minimum Dynamic Output Current	5.5	_	_	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	_	_	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	_	8.0	80	μΑ	$V_{IN} = V_{CC}$ or GND	

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms - See AND8277/D at www.onsemi.com)

			74ACT			74	CT		
Symbol	Parameter	V _{CC} * (V)		T _A = +25°C C _L = 50 pF		T _A = -40°C C _L =	C to +85°C 50 pF	Unit	Figure No.
			Min	Тур	Max	Min	Max		
t _{PLH}	Propagation Delay Data to Output	5.0	2.0	6.5	9.0	1.5	10.0	ns	3–5
t _{PHL}	Propagation Delay Data to Output	5.0	2.0	7.0	9.0	1.5	10.0	ns	3–5
t _{PZH}	Output Enable Time	5.0	1.5	6.0	8.5	1.0	9.5	ns	3–7
t _{PZL}	Output Enable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–8
t _{PHZ}	Output Disable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–7
t _{PLZ}	Output Disable Time	5.0	2.5	7.5	10.0	2.0	10.5	ns	3–8

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

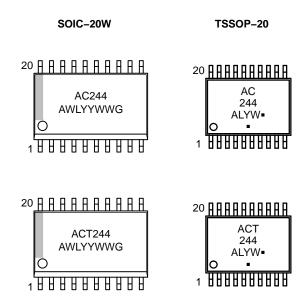
Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	45	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74AC244DWG		38 Units / Rail
MC74AC244DWR2G	SOIC-20	1000 / Tape & Reel
MC74ACT244DWG	(Pb-Free)	38 Units / Rail
MC74ACT244DWR2G		1000 / Tape & Reel
MC74AC244DTR2G	TSSOP-20	2500 / Tape & Reel
MC74ACT244DTR2G	(Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MARKING DIAGRAMS



A = Assembly Location

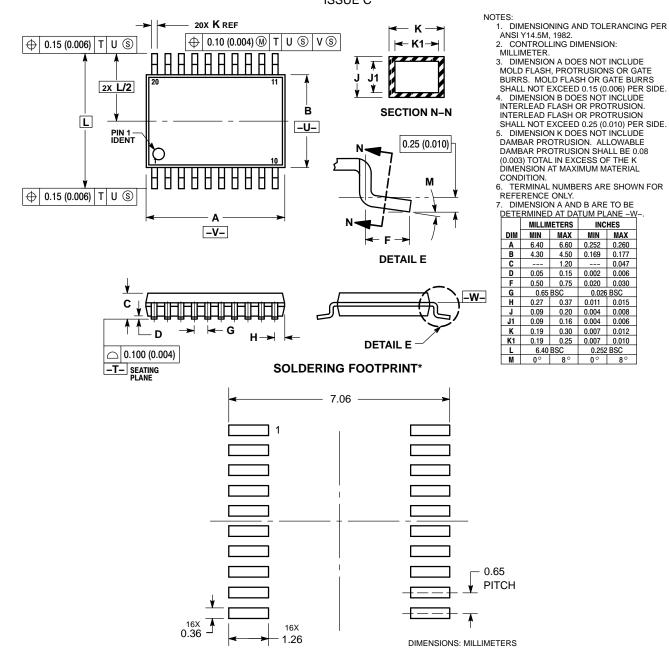
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

PACKAGE DIMENSIONS

TSSOP-20 DT SUFFIX CASE 948E-02 ISSUE C



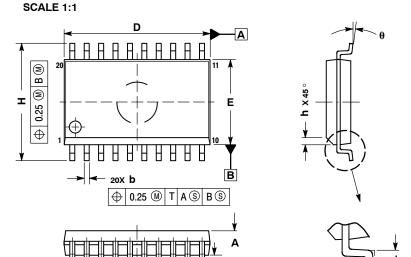
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





SOIC-20 WB CASE 751D-05 **ISSUE H**

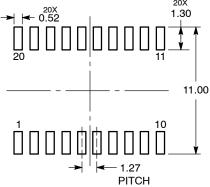
DATE 22 APR 2015



- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

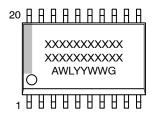
	MILLIMETERS							
DIM	MIN	MAX						
Α	2.35	2.65						
A1	0.10	0.25						
b	0.35	0.49						
С	0.23	0.32						
D	12.65	12.95						
E	7.40	7.60						
е	1.27	BSC						
Н	10.05	10.55						
h	0.25	0.75						
L	0.50	0.90						
A	0 °	7 °						

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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